

Description

CUSTOMIZED MICROELECTRONIC DEVICE AND METHOD FOR MAKING CUSTOMIZED ELECTRICAL INTERCONNECTIONS

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TECHNICAL FIELD

The present invention relates to methods for electrically coupling and electrically coupled input/output bond pads of a microelectronic device.

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BACKGROUND ART

Integrated circuit devices typically comprise a group of circuits, each of which is formed of interconnected elements fabricated on a semiconductor substrate. Certain circuits on an integrated circuit device are designed to be electrically separate so that they may be customized after the wafer-fabrication process. These integrated circuit devices can be customized by electrically connecting the separate circuits. Because gaps disposed between typical integrated circuits are relatively small, it can be difficult to make typical wire bond connections with a wire bonding tool known in the art. Typical wire bond connections include ball and wedge bonds having a ball and tail. The following patents illustrate different types of methods for electrically connecting separate circuits and apparatuses having electrical connections.

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U.S. Patent No. 4,298,856 to Schuchardt discloses establishing short circuit connections between different pairs of the bonding pads of a resistor by use of a simple glob of solder. Thus, the bonding pads must likely be solderable.

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U.S. Patent No. 6,262,434 to Kalb describes an integrated circuit including a first circuit structure, a first conductive bonding pad coupled to the first circuit structure, a second circuit structure, and a second

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conductive bonding pad coupled to the second circuit structure. The first conductive bonding pad is arranged to be separated from the second conductive bonding pad by a gap having a gap dimension. The gap dimension is
5 configured to be bridged by a wire bond formed by a wire bonding tool, thereby electrically coupling the first conductive bonding pad to the second conductive bonding pad. It is possible to bridge the two bonding pads with a single bonding wire because the gap is bigger than that
10 of the gap formed by a conventional semiconductor processing technique.

U.S. Patent No. 6,169,331 to Manning et al. describes electronically coupling bond pads of a microelectronic device to each other. A first conductive
15 member extends between the two bond pads and a second conductive member extends from one of the pads to a position external to the device. A combination of ball and wedge wire bonds, each having a ball and tail, is used to electrically connect the bond pads of the device.
20 Where a conductive link already exists between the bond pads, the link between the two bond pads can be used to supplement the internal circuitry of the microelectronic device. Where a conductive link does not exist between the bond pads, the link between the two bond pads can be
25 used to modify or repair the electronic device after it has been manufactured. The spacing between the bond pads of one device and the bond pads of another device may be large enough to allow for typical wire bonds.

It is an object of the present invention to
30 provide a method for electrically connecting input/output bond pads of a microelectronic device.

It is another object of the present invention to provide an apparatus having electrically connected input/output bond pads on a microelectronic device.

It is another object of the present invention to provide a method for customizing an integrated circuit device.

5 SUMMARY OF THE INVENTION

The above and other objects have been achieved by a method including bonding first and second conductive stud balls to respective first and second conductive input/output bond pads of a microelectronic device and
10 bonding a third conductive stud ball to the first and second conductive stud balls with a wire bonding tool in a "stud ball" mode or other tool capable of bonding stud balls. A wire bonding tool in stud ball mode bonds only a stud ball to the desired surface, instead of both a
15 ball and tail. The stud ball bonding may occur at the packaging assembly level and is easily integrated into the standard automatic wire bonding process.

The microelectronic device of the present invention includes a semiconductor substrate having an
20 integrated circuit with circuitry electrically connected to conductive input/output bond pads. Each input/output bond pad of at least one pair of the input/output pads has a bonded conductive stud ball. An additional third conductive stud ball is bonded to the stud balls on the
25 bond pad pairs. The input/output bond pads are disposed proximate to one another and may be separated by a standard distance utilized in the art. In one example, the conductive stud ball is a gold stud ball and the input/output bond pads are aluminum.

30 A user may customize the integrated circuit by selecting, from a plurality of input/output bond pads, a particular pair of input/output bond pads on a microelectronic device corresponding to circuitry to be electrically connected.

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BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a diagram of an integrated circuit chip and associated leads and pins.

5 Fig. 2A is a partial side view of the integrated circuit chip of Fig. 1 having a first stud ball bonded to a first input/output bond pad.

Fig. 2B is a partial side view of the integrated circuit chip of Fig. 2A having a second stud ball bonded to a second input/output bond pad.

10 Fig. 2C is a partial side view of the integrated circuit chip of Fig. 2B having a third stud ball bonded to the first and second stud balls.

Fig. 2D is a partial top view of the integrated circuit chip of Fig. 2C.

15 Fig. 2E is a partial perspective view of the integrated circuit chip of Fig. 2D.

Fig. 3 is a partial side view of a wire bonding tool.

20 DETAILED DESCRIPTION OF THE INVENTION

With reference to Fig. 1, stud ball bond arrangement 12 of the present invention is seen. An integrated circuit device such as integrated circuit chip 10, including a plurality of input/output bond pads 14, has for example, three stud ball bond arrangements 12 of the present invention. In the example shown in Fig. 1, three pairs 16a, 16b, and 16c of conductive input/output bond pads 14 disposed on a surface 30 of the integrated circuit chip 10 are electrically connected by the stud ball bond arrangements 12a, 12b, and 12c of the present invention. Any desired number of pairs 16 of input/output bond pads may be electrically connected with a corresponding number of stud ball bond arrangements 12 of the present invention. If desired, the stud ball bond arrangement 12 of the present invention may be formed post wafer fabrication and at stages before or after

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package level assembly. When conductive stud balls are bonded in accord with the present invention, select input/output bond pads and the circuitry connected to the select input/output bond pads are electrically connected.

5 The integrated circuit chip 10 is mounted on a substrate, such as a chip carrier 17. The chip carrier 17 includes leads 18 and pins 20 which are typically electrically connected to input/output bond pads 14 of the plurality of input/output bond pads of the integrated
10 circuit chip. Electrical connections to the leads 18 and pins 20 may occur at the package assembly level, though such electrical connections are not shown here.

 Referring to Figs. 2A-2E and Fig. 3, a method of forming the stud ball arrangement 12a with regard to
15 bond pair 16a is shown. This method is applicable when forming additional stud ball arrangements 12 for other bond pairs 16 of an integrated circuit chip. A first input/output bond pad 14a is spaced apart from and proximate to a second input/output bond pad 14b to which
20 it is paired. On a standard integrated circuit chip, the input/output bond pads are typically spaced about 60-65 microns apart, however, other spacing may be used in conjunction with the present invention. In one example, the input/output bond pads 14a and 14b have dimensions of
25 80 microns by 80 microns. The input/output bond pads 14a and 14b are in electrical communication with circuitry, for example circuits 26 and 28, represented with the illustrated perforations, of integrated circuit chip 10.

 In each select input/output bond pad pair 16a,
30 a first conductive stud ball 32 is bonded to the first input/output bond pad 14a, a second conductive stud ball 34 is bonded to the second input/output bond pad 14b, and a third conductive stud ball 36 is bonded to both first and second conductive stud balls 32 and 34, forming the
35 stud ball arrangement 12a. The stud balls desirably comprise a metal that can be formed into a fine wire for

the standard ball bonding process. The metal used to form the stud balls should form a reliable bond with the integrated circuit chip's input/output bond pad. For example, gold alloys reliably bond with aluminum metal input/output bond pads on a typical integrated circuit chip, and thus may be used to form stud balls. Also, copper wire for standard ball bonding can be used to form the stud balls. Copper reliably bonds to copper input/output bond pads. In one example, the stud balls 32, 34, and 36 are gold and the input/output bond pads 14a and 14b are aluminum. In another example, the stud balls 32, 34, and 36 are copper and the input/output bond pads 14a and 14b are copper.

Stud balls are typically twice the diameter of the bond wire. In one example, the bond wire diameter is 1mm and the stud ball has a diameter of 2mm. In one example, the thickness of the stud ball is approximately 1.5 mm.

Referring back to Fig. 1, the input/output bond pads 14 provide means by which electrical signals are input or output from the underlying connected circuitry of the integrated circuit chip 10 to enable the operation of the underlying circuits. In one example, one input/output bond pad of the bond pad pair is utilized to input or output a int_osc_en_vdd signal utilized for internal oscillator enable power where the other input/output bond pad of the same bond pair is utilized to input or output a int_osc_en signal utilized for internal oscillator enable. Therefore, when the input/output bond pad pair 16 is connected with the stud ball bond arrangement 12, electrical connecting of the circuitry associated with these signals occurs.

Other examples of input/output bond pad pairs on an integrated circuit electrically connected by means of the stud ball bond arrangement of the present

invention are bond pad pairs utilized for the input or output of the following signals:

int_osc_en and int_osc_en_vss for connecting the internal oscillator enable to ground;

5 den_cs0 and den_cs0_vss for connecting the density chip select 0 to ground; and

den_cs1 and den_cs1_vss for connecting the density chip select 1 to ground.

10 With reference to Fig. 3, a wire bonding tool 38, known in the art, is seen. In one example, the wire bonding tool utilized in the present invention is a K&S 8020 wire bonding tool. Other wire bonding tools and other tools capable of bonding stud balls may be utilized
15 in the present invention. The wire bonding tool may be a type that bonds a stud ball to the select location using thermo-sonic, ultrasonic, or compression bonds. The resulting stud ball size and shape is determined by the bonding tool and the bonding tool settings. The bonding
20 tool parameters and related equipment parameters affect the geometry of the stud ball. The stud ball need not be spherical and may take the shape of a bump, for example.

 With reference to Figs. 2A and 3, the wire bonding tool 38 is programmed to be or placed in stud
25 ball bonding mode and the first conductive stud ball 32 is bonded to conductive input/output bond pad 14a of the integrated circuit device 10 with the wire bonding tool 38.

 With reference to Figs. 2B and 3, the wire bonding tool 38 in stud ball bonding mode is used to bond
30 a second conductive stud ball 34 to the conductive input/output bond pad 14b spaced apart from and disposed proximate to the input/output bond pad 14a.

 With reference to Figs. 2C, 2D and 3, the wire bonding tool 38 in stud ball bonding mode is used to bond
35 a third conductive stud ball 36 to the first and second

conductive stud balls 32 and 34, electrically connecting the underlying circuits. With the stud ball bond arrangement 12 of the present invention, the underlying circuits, in one example circuits 26 and 28, are
5 electrically connected customizing the integrated circuit chip.

After the desired number of stud ball bonding arrangements 12 of the present invention have been bonded to select input/output bond pad pairs, the wire bonding
10 tool may be programmed to be or placed in a standard bonding mode to wedge or ball bond together desired structures with a typical ball and tail structure. In the standard bonding mode, the integrated circuit device may be electrically connected to the device carrier.

15 The present invention allows a user to select which circuits of an integrated circuit device he desires to electrically connect through select input/output bond pad pairs corresponding to the circuits to be electrically connected by means the stud ball bond
20 arrangement of the present invention.